OUR PROPOSED CLAIMS Serial No. 10/511,450 Reflow Soldering Apparatus

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Claim 1(amended): A reflow soldering apparatus comprising a conveyor to transport circuit boards mounted with electronic components into multiple chambers, blowing means installed in said chambers and having vertical rotating shafts respectively, a first casing member having a fan storage section housing said blowing means and a gas quide section extending from said fan storage section in a direction perpendicular to a transport line of said conveyor, a second casing member connected to said gas quide section of said first casing member and having multiple heated gas nozzle holes on the side facing said conveyor, and a gas circulated by said blowing means and heated while passing through a heater installed within said apparatus and entered said second casing member from said gas guide section of said first casing member to be blown from said nozzle holes onto said circuit boards on said conveyor, wherein said adjacent blowing means are arrayed offset to the left and right in a direction perpendicular to the transport line of said conveyor, said adjacent blowing means are installed to overlap as seen horizontally from a direction perpendicular to the transport line ofsaid conveyor, and said first casing member and said second casing member have a width smaller than the diameter of said blowing means.

Claim 2(canceled)

Claim 3 (amended): A reflow soldering apparatus comprising a conveyor to transport circuit boards mounted with electronic components into multiple chambers, blowing means installed in said chambers and having vertical rotating shafts respectively, a first casing member having a fan storage section housing said blowing means and a gas guide section extending from said fan storage section in a direction perpendicular to a transport line of said conveyor, a second casing member connected to said gas quide section of said first casing member and having multiple heated gas nozzle holes on the side facing said conveyor, and a gas circulated by said blowing means and heated while passing through a heater installed within said apparatus and entered said second casing member from said gas guide section of said first casing member to be blown from said nozzle holes onto said circuit boards on said conveyor, wherein said adjacent blowing means are arrayed offset up and down in a direction perpendicular to the transport line of said conveyor, said adjacent blowing means are installed to overlap as seen vertically from a direction perpendicular to the transport line of said conveyor, and said first casing member and said second casing member have a width smaller than the diameter of said blowing means.

Claim 4 (canceled)

Claims 5-7 (canceled)

Claim 8 (amended): A reflow soldering apparatus comprising a conveyor to transport circuit boards mounted with electronic components into multiple chambers, blowing means installed in said chambers and having vertical rotating shafts respectively, a first casing member having a fan storage section housing said blowing means and a gas quide section extending from said fan storage section in a direction perpendicular to a transport line of said conveyor, a second casing member connected to said gas guide section of said first casing member and having multiple heated gas nozzle holes on the side facing said conveyor, and a gas circulated by said blowing means and heated while passing through a heater installed within said apparatus and entered said second casing member from said gas guide section of said first casing member to be blown from said nozzle holes onto said circuit boards on said conveyor, wherein said adjacent blowing means are arrayed offset to the left and right in a direction perpendicular to the transport line of said conveyor, said blowing means storage sections of the adjacent first casing members are installed to overlap as seen horizontally from a direction perpendicular to the transport line of said conveyor, and

said first casing member and said second casing member have a width smaller than the diameter of said blowing means.

Claim 9 (canceled)

Claim 10: (amended) A reflow soldering apparatus comprising a conveyor to transport circuit boards mounted with electronic components into multiple chambers, blowing means installed in said chambers and having vertical rotating shafts respectively, a first casing member having a fan storage section housing said blowing means and a gas guide section extending from said fan storage section in a direction perpendicular to a transport line of said conveyor, a second casing member connected to said gas quide section of said first casing member and having multiple heated gas nozzle holes on the side facing said conveyor, and a gas circulated by said blowing means and heated while passing through a heater installed within said apparatus and entered said second casing member from said gas quide section of said first casing member to be blown from said nozzle holes onto said circuit boards on said conveyor, wherein said adjacent blowing means are arrayed offset up and down in a direction perpendicular to the transport line of said-conveyor, said blowing means storage sections of the adjacent first casing members are installed to overlap as seen vertically from a direction perpendicular to the transport line of said conveyor, and

said first casing member and said second casing member have a width smaller than the diameter of said blowing means.

Claim 11(canceled)